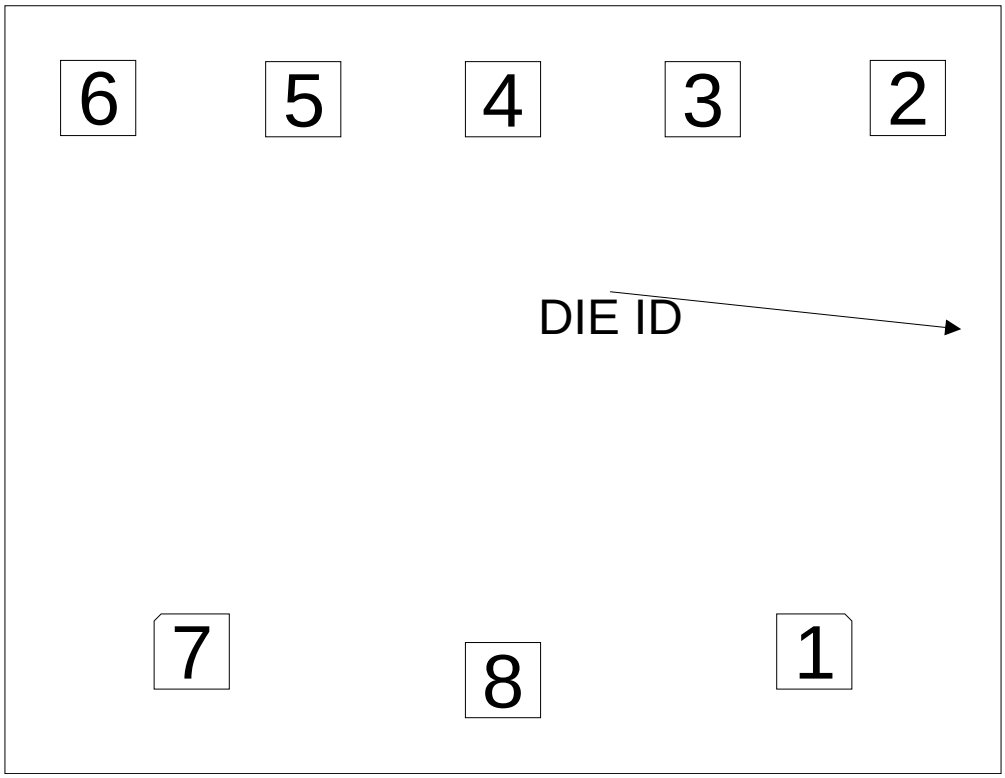
LM158A MDR MCD2630A
SMD#5962R8771002V9A
LOW POWER DUAL OPERATIONAL AMPLIFIER

DEC 11, 2008

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM158D	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	D	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1219.20µm x 939.80µm 48.0mils x 37.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	244µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(D-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
OUTPUT A	1	381	-321	92	x	92
INPUT A -	2	496	357	92	x	92
INPUT A +	3	245	356	92	x	92
GND	4	0	356	92	x	92
INPUT B +	5	-245	356	92	x	92
INPUT B -	6	-496	357	92	x	92
OUTPUT B	7	-381	-321	92	x	92
V +	8	0	-356	92	x	92

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Notes

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